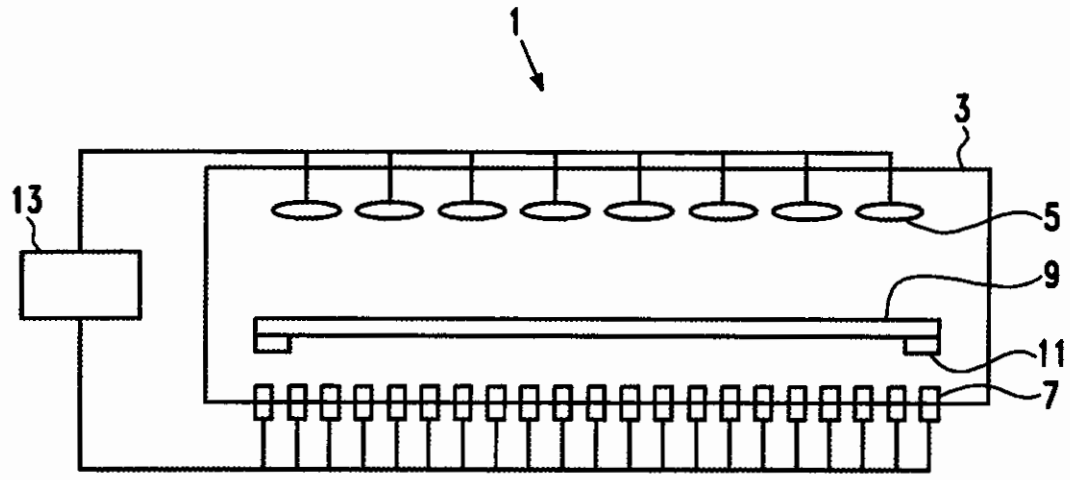


Fig.1

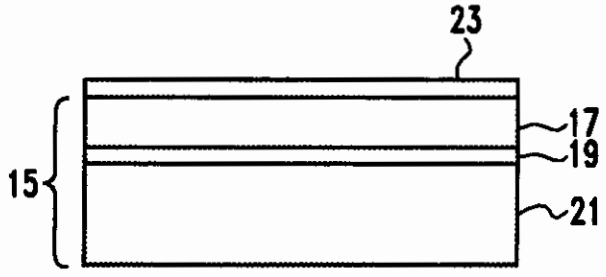


Fig.2a

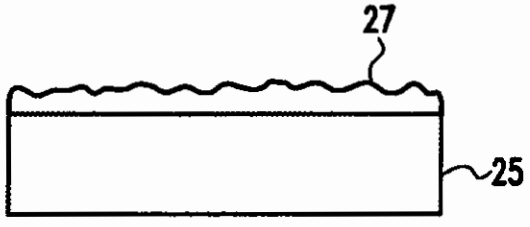


Fig.2b

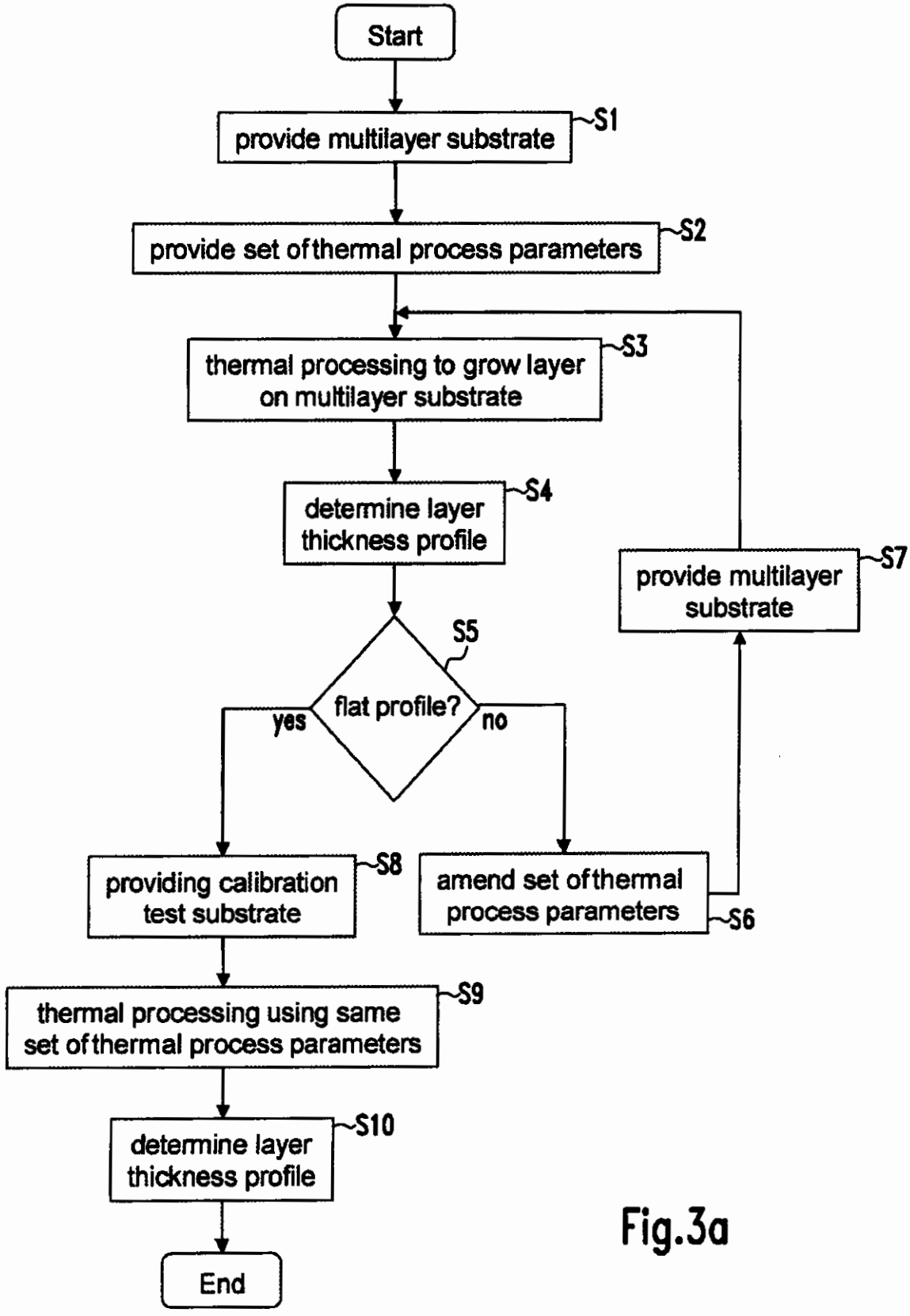

Start
provide multilayer substrate
S1
provide set of thermal process parameters
S2
thermal processing to grow layer on multilayer substrate
S3
determine layer thickness profile
S4
S5
flat profile?
yes
no
provide multilayer substrate
S7
providing calibration test substrate
S8
amend set of thermal process parameters
S6
thermal processing using same set of thermal process parameters
S9
determine layer thickness profile
S10
End

Fig.3a

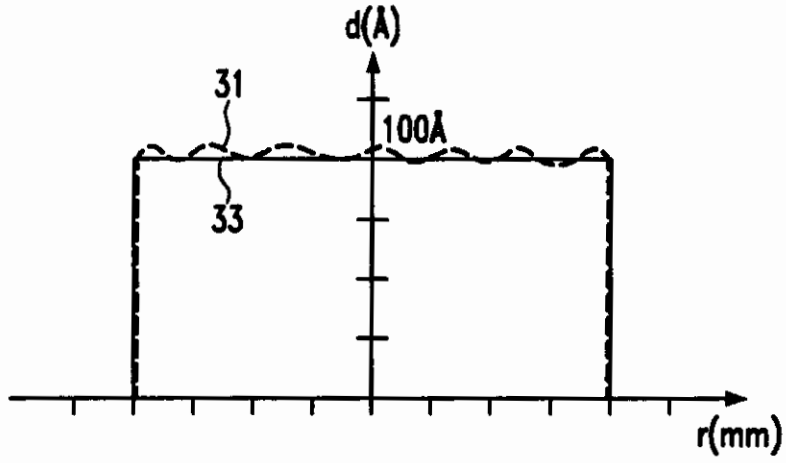


Fig.3b

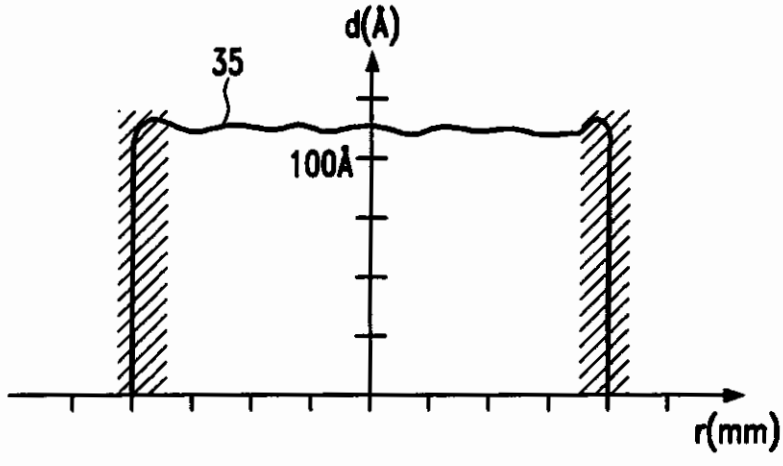


Fig.3c

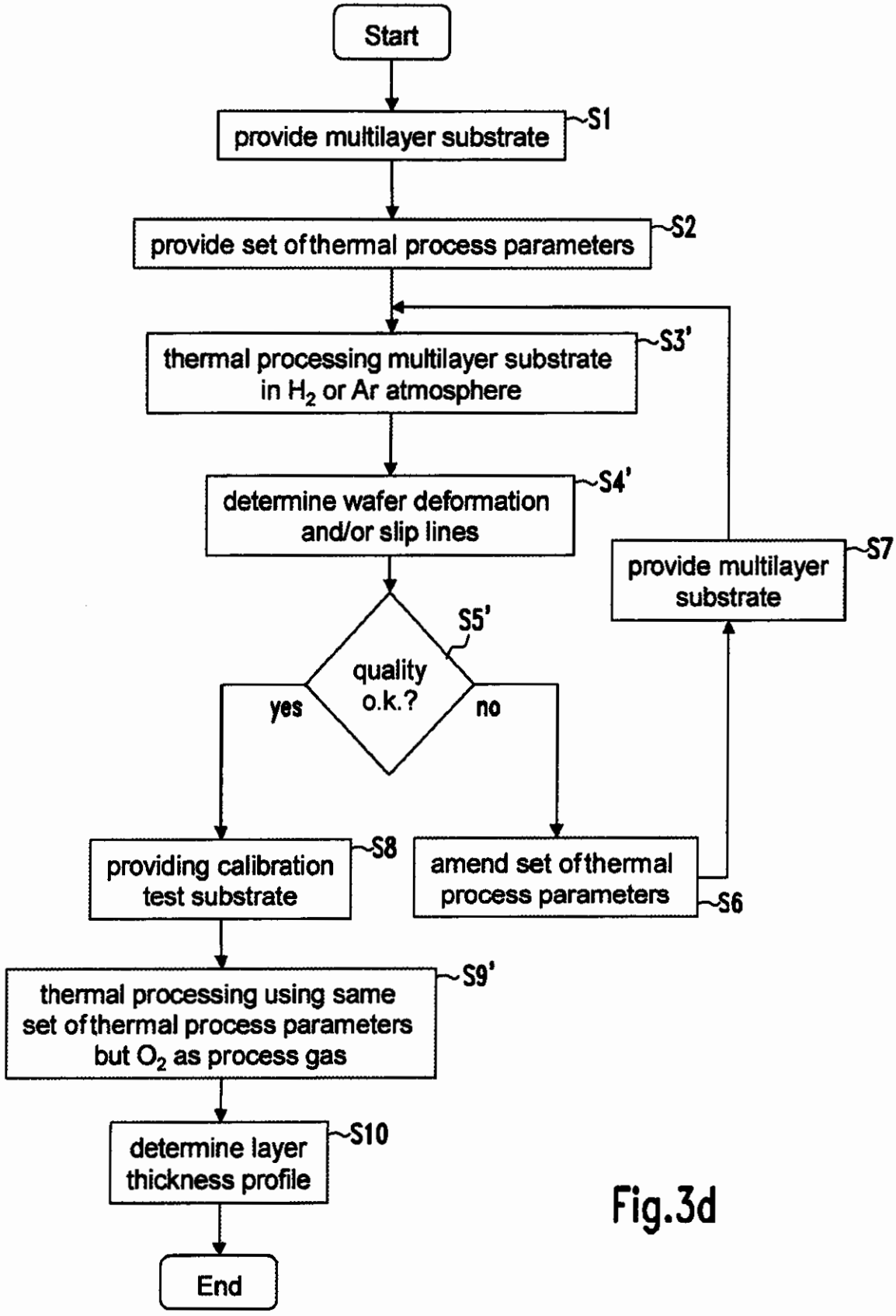

Start
provide multilayer substrate
S1
provide set of thermal process parameters
S2
thermal processing multilayer substrate in H_2 or Ar atmosphere
S3'
determine wafer deformation and/or slip lines
S4'
quality o.k.?
S5'
yes
no
providing calibration test substrate
S8
amend set of thermal process parameters
S6
provide multilayer substrate
S7
thermal processing using same set of thermal process parameters but O_2 as process gas
S9'
determine layer thickness profile
S10
End

Fig.3d

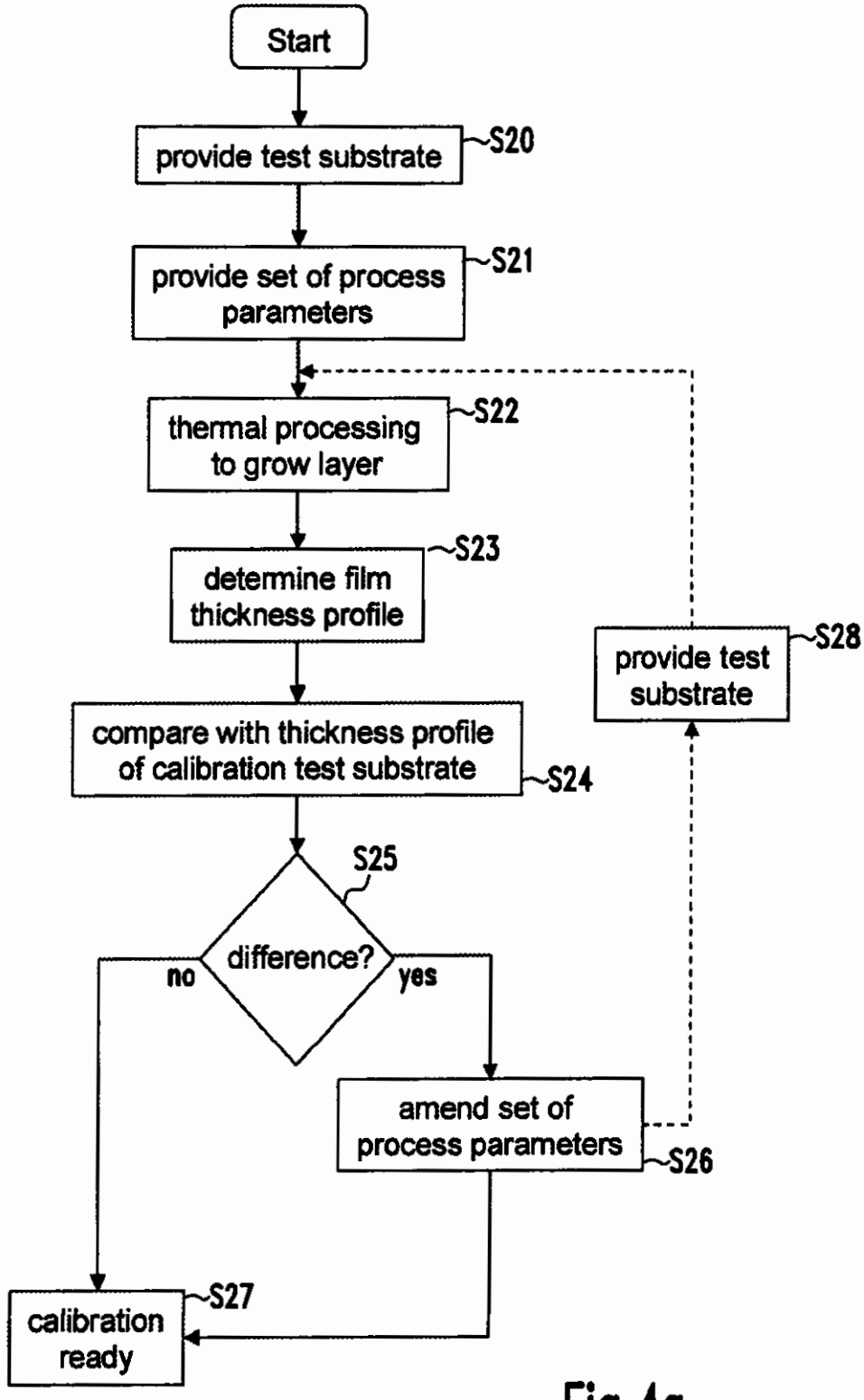

Start
provide test substrate
S20
provide set of process parameters
S21
thermal processing to grow layer
S22
determine film thickness profile
S23
compare with thickness profile of calibration test substrate
S24
S25
difference?
no
yes
amend set of process parameters
S26
provide test substrate
S28
calibration ready
S27

Fig.4a

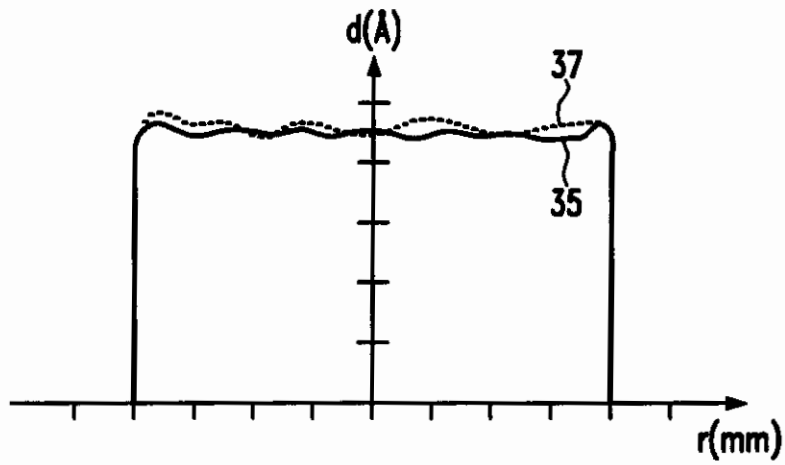


Fig.4b